

Thermal Property Manipulation of Crystalline Materials through Ion Implantation

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Ion Beams

Thrusters (NASA's 2.3 kW NSTAR)

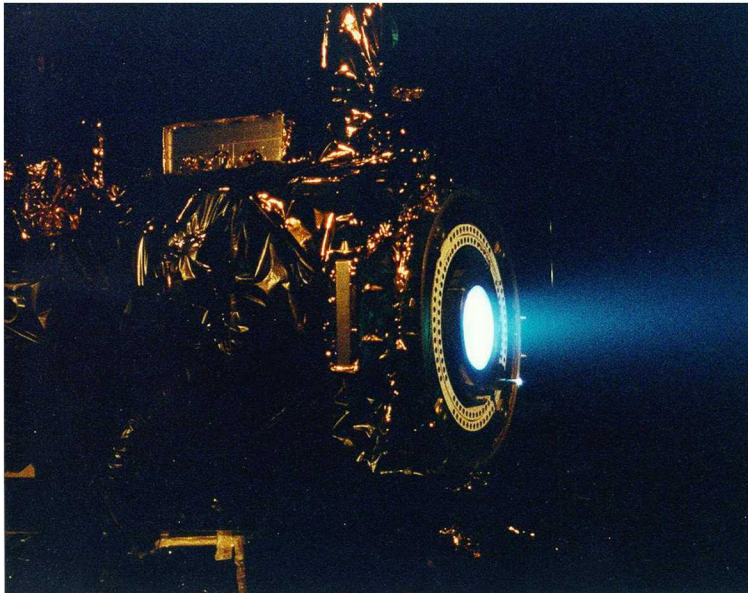


Image source: https://en.wikipedia.org/wiki/Ion_beam

Manufacturing (Etching/sputtering/milling) (Zeiss nanofluidic channel)

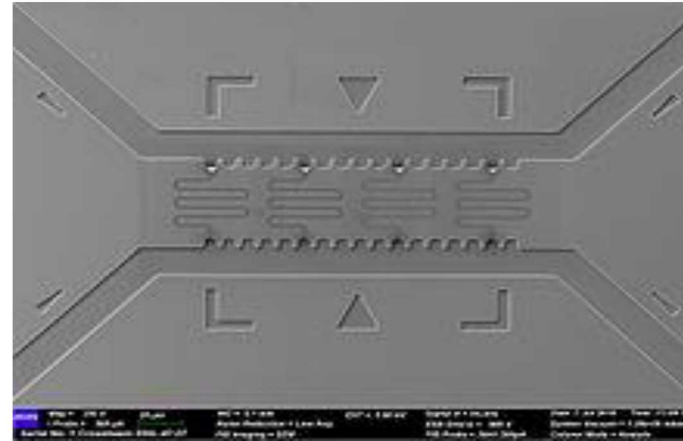


Image source: https://en.wikipedia.org/wiki/Ion_beam

Microscopy (FIB)

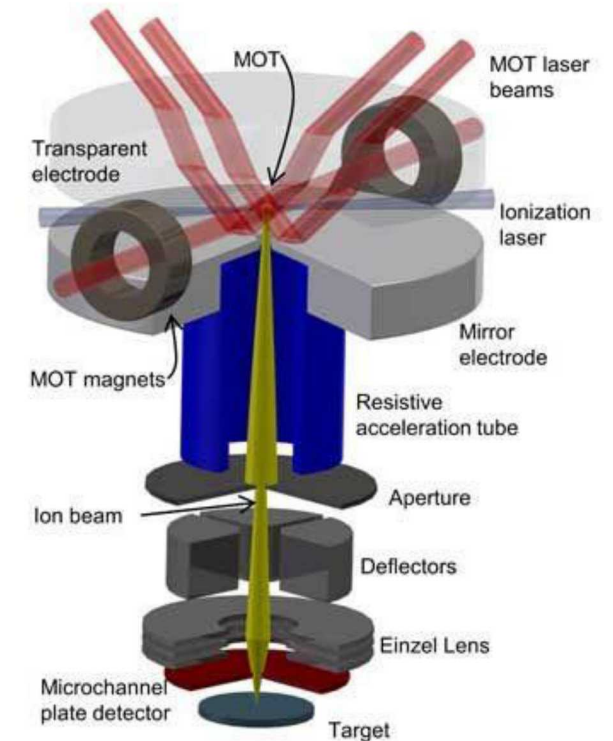


Image source: <https://tinyurl.com/yyc3nler>

Ion Implantation

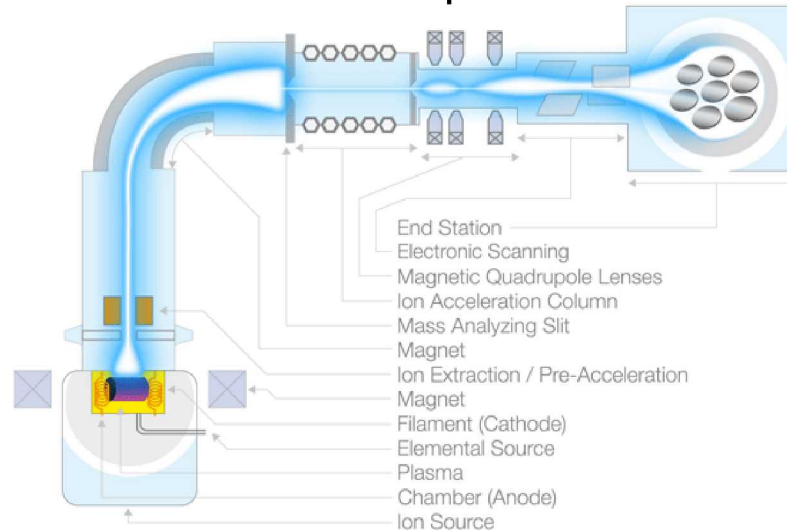


Image source: <https://www.plansee.com/en/products/components/spare-parts-for-ion-implantation.html>

Ion Implantation

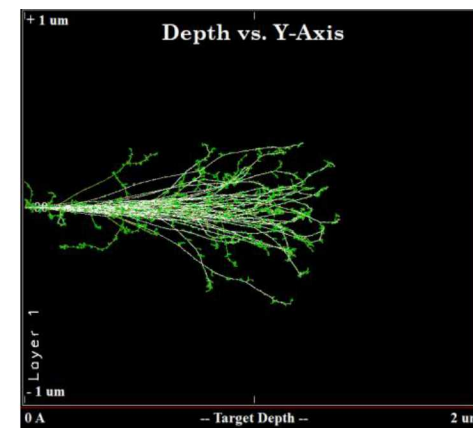
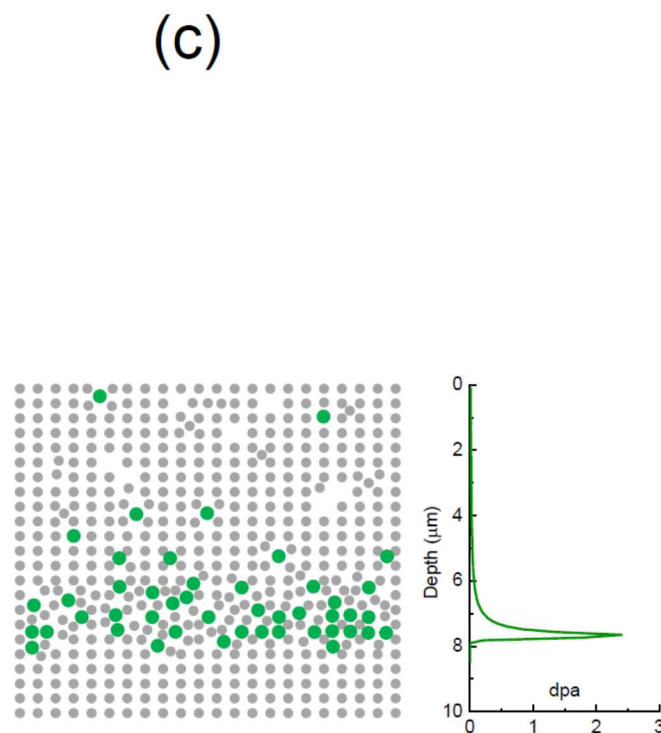
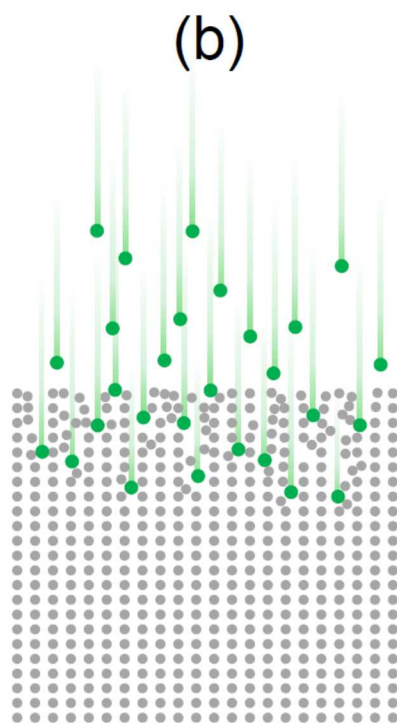
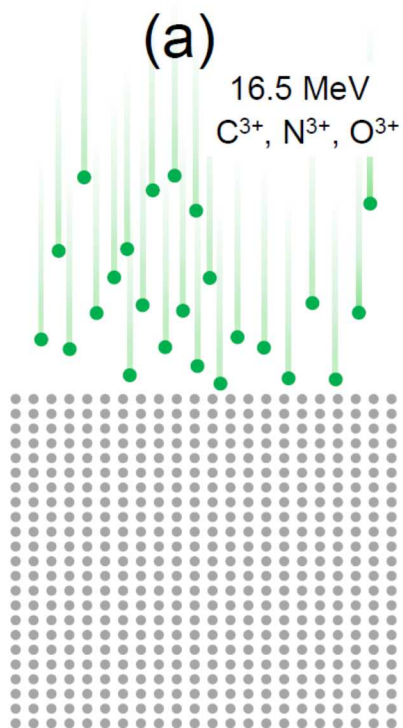
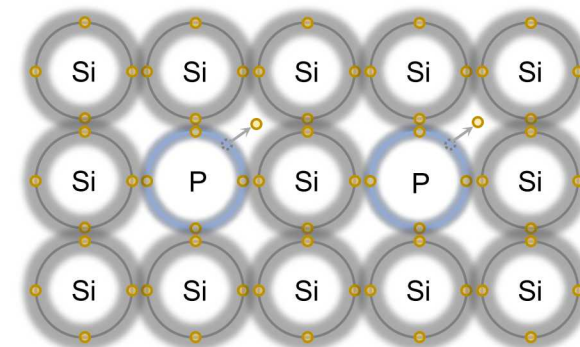
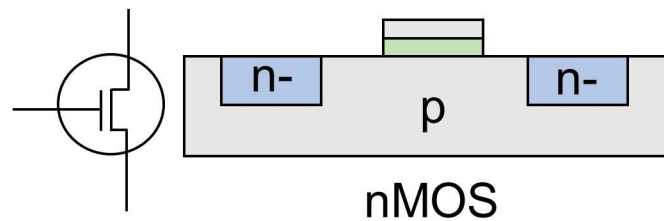
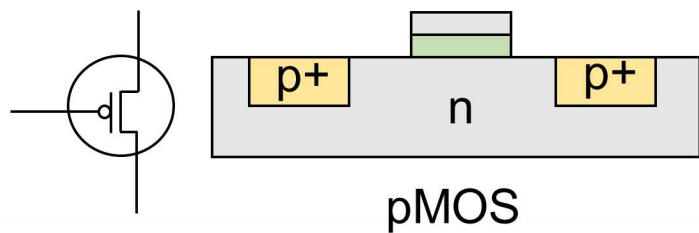


Image Source: <https://commons.wikimedia.org/wiki/File:Billard.JPG>

Ion Implantation



Image source: <http://www.pelletron.com/products/snics/>

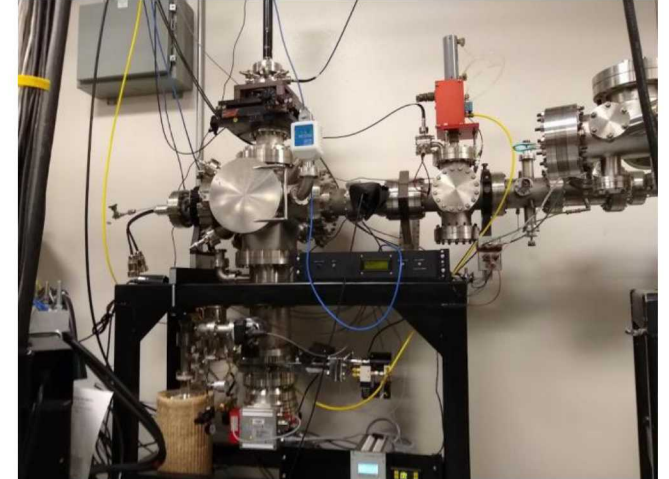
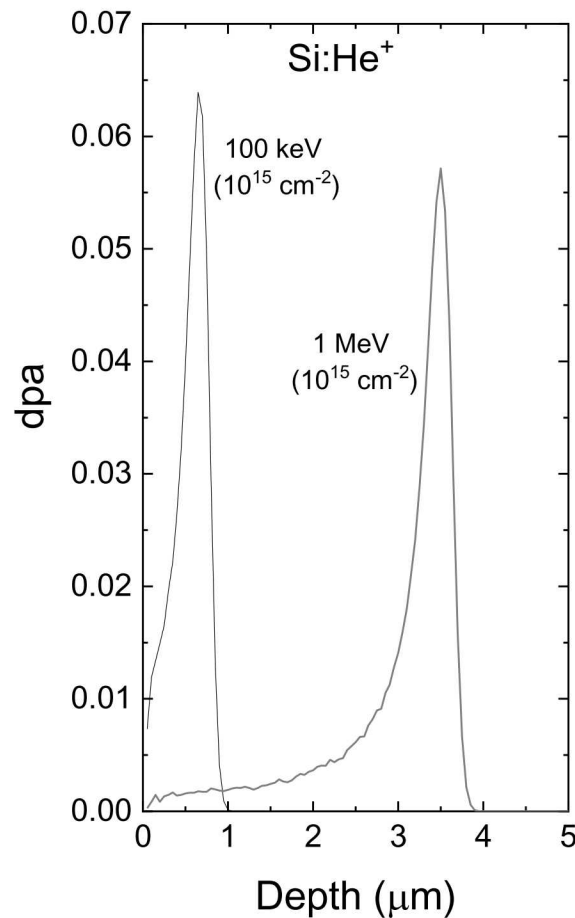


Image source: <http://www.sandia.gov/LabNews/100521.html>

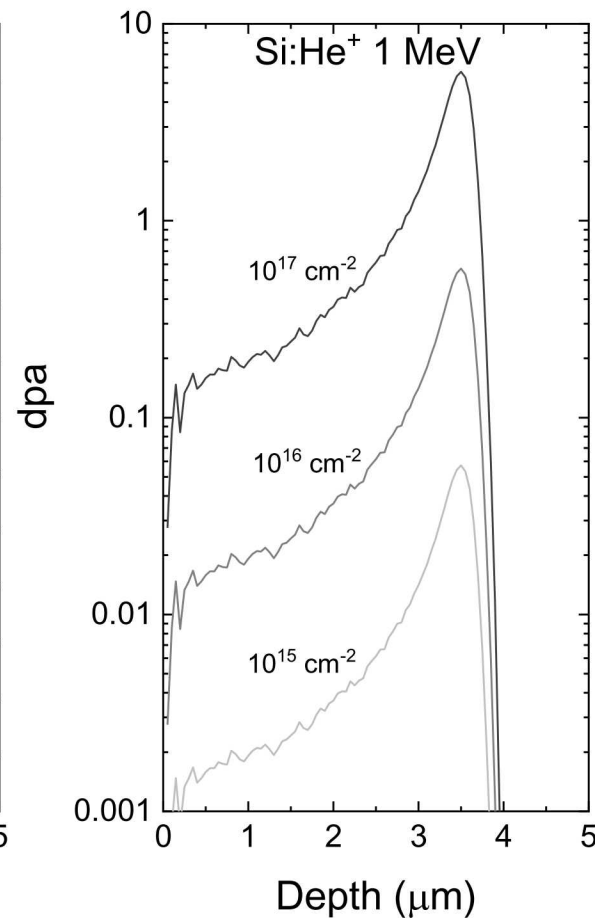


Parameters of implantation

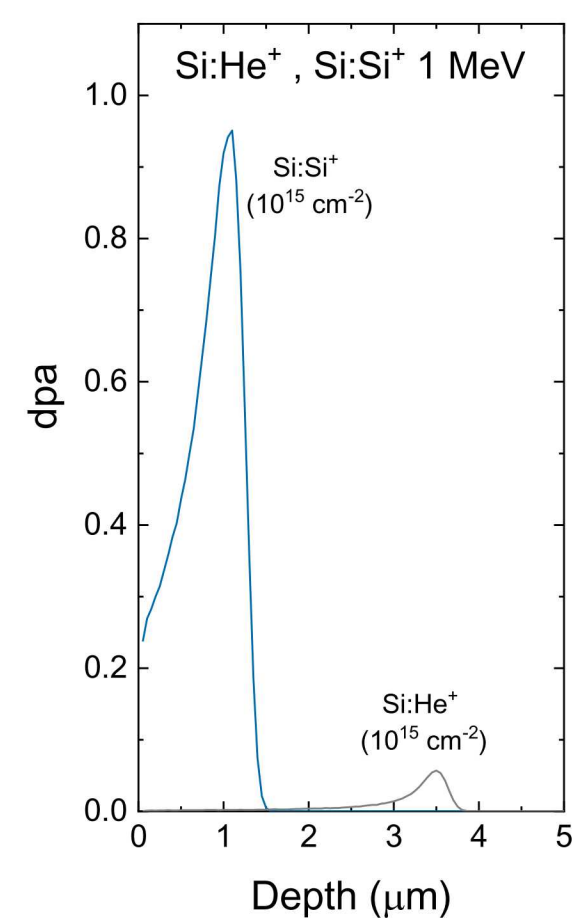
- Ion energy



- Fluence



- Ion species



Crystallographic defects and thermal conductivity

- Callaway:

$$\kappa = \frac{1}{6\pi^2} \sum_j \int \hbar \omega_j(k) k^2 \frac{\partial f}{\partial T} v_j^2(k) \tau_j(k) dk$$

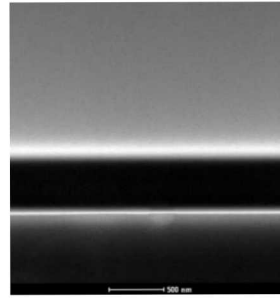
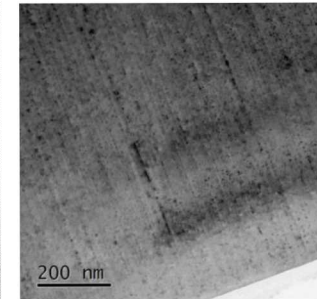
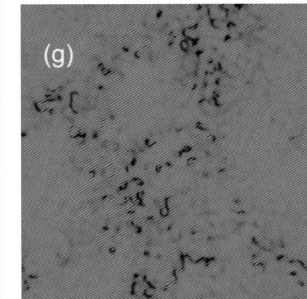
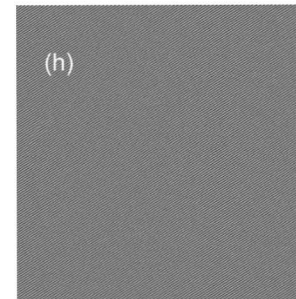
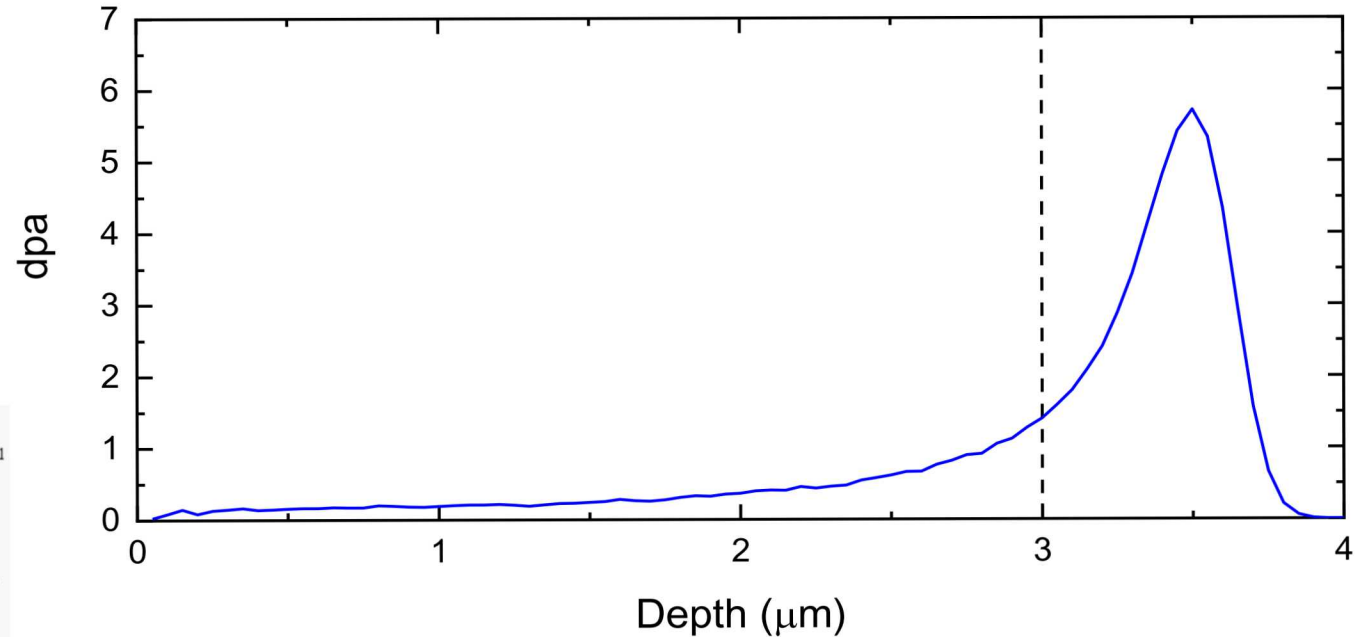
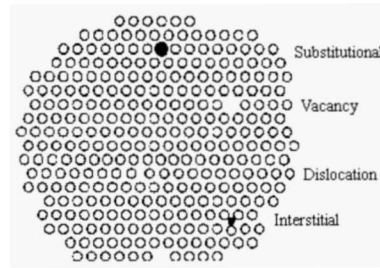
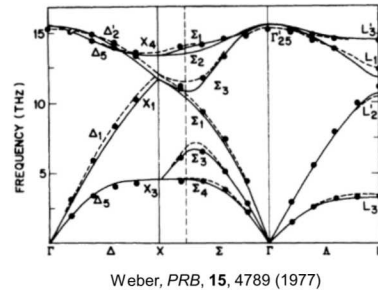
- Matthiessen's Rule:

$$\frac{1}{\tau} = \frac{1}{\tau_{Ph}} + \frac{1}{\tau_{Imp}} + \frac{1}{\tau_{Def}} + \dots$$

- Klemens:

$$\tau_{Def}^{-1} = \frac{\omega(k)^4 \delta^3 \Gamma_i}{4\pi v_j^3(k)}$$

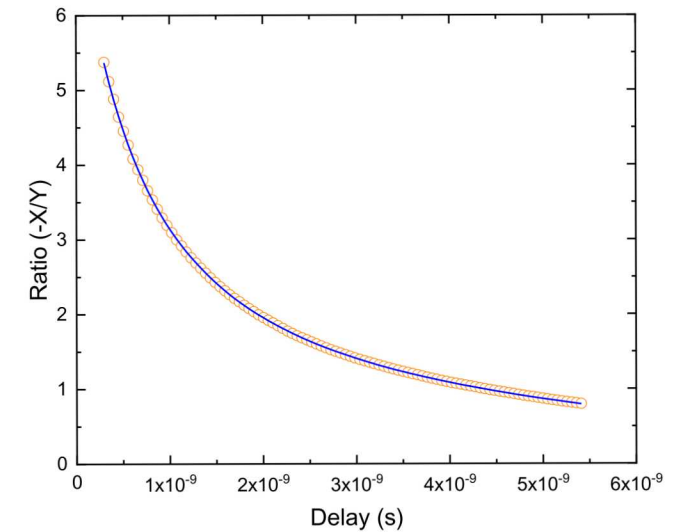
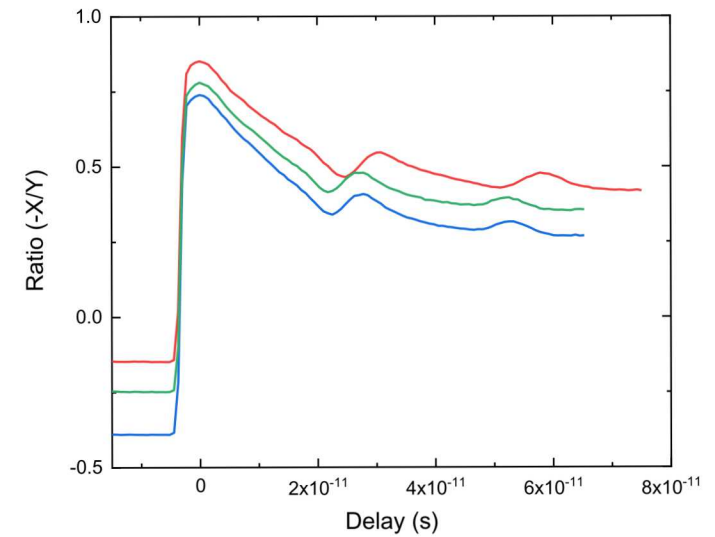
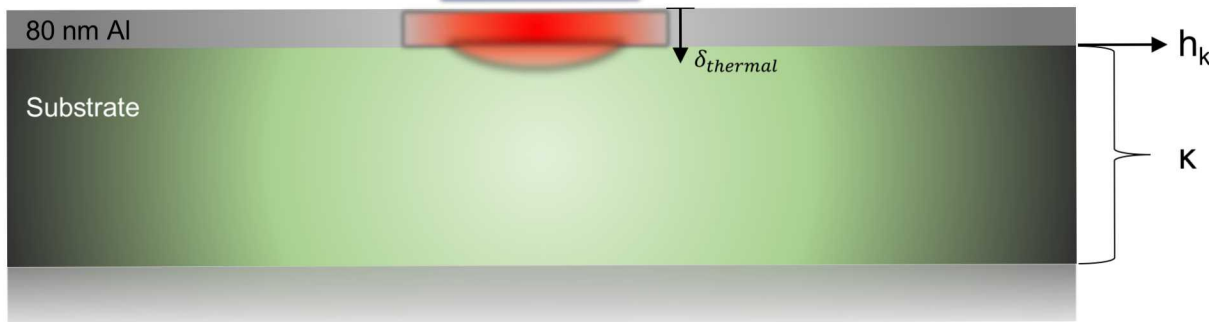
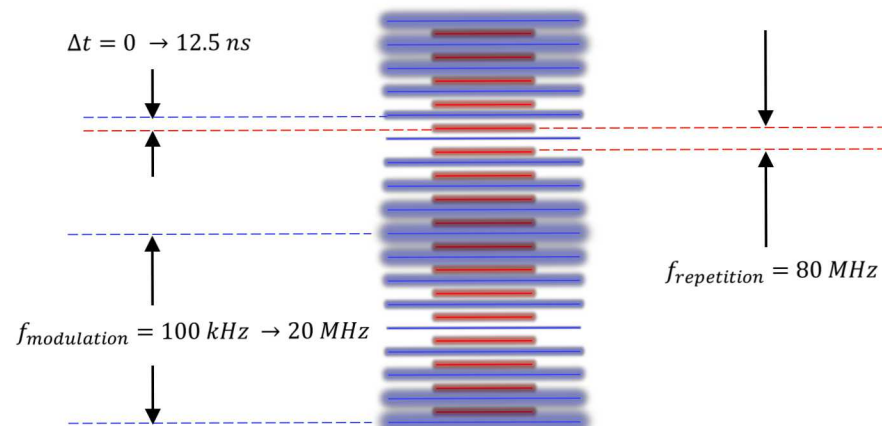
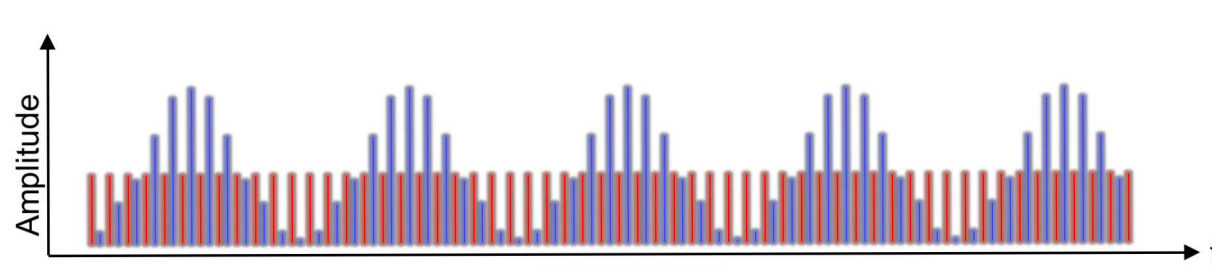
$$\Gamma_i = x_i \left[\left(\frac{\Delta M_i}{M} \right)^2 + 2 \left(\left(\frac{\Delta G_i}{G} \right) - 2 * 3.2\gamma \left(\frac{\Delta \delta_i}{\delta} \right) \right)^2 \right]$$



Scott *et al.*, *PRM*, 2, 095001 (2018)

Abdullaev *et al.*, *Acta Materialia*, pre-print (2019)

Time domain thermoreflectance (TDTR)



$^{28,29}\text{Si}^+$ in silicon



Image source:
[https://en.wikipedia.org/wiki/Boule_\(crystal\)](https://en.wikipedia.org/wiki/Boule_(crystal))

Isotope	Prevalence (%)
^{28}Si	92.22
^{29}Si	4.69

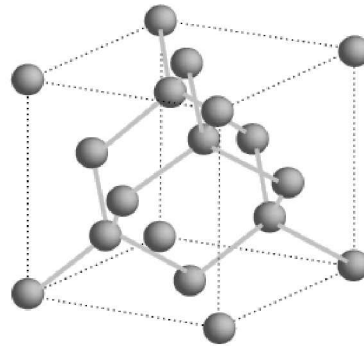
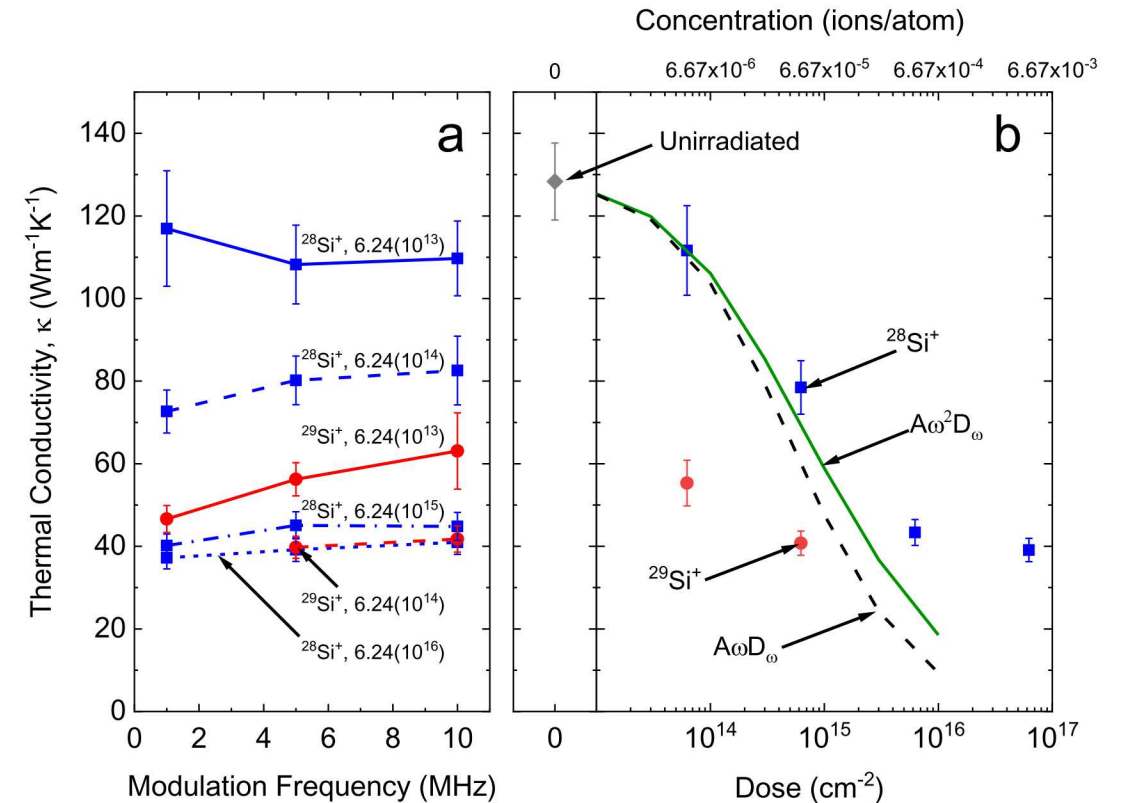


Image source: <http://hyperphysics.phy-astr.gsu.edu/hbase/Solids/sili2.html>

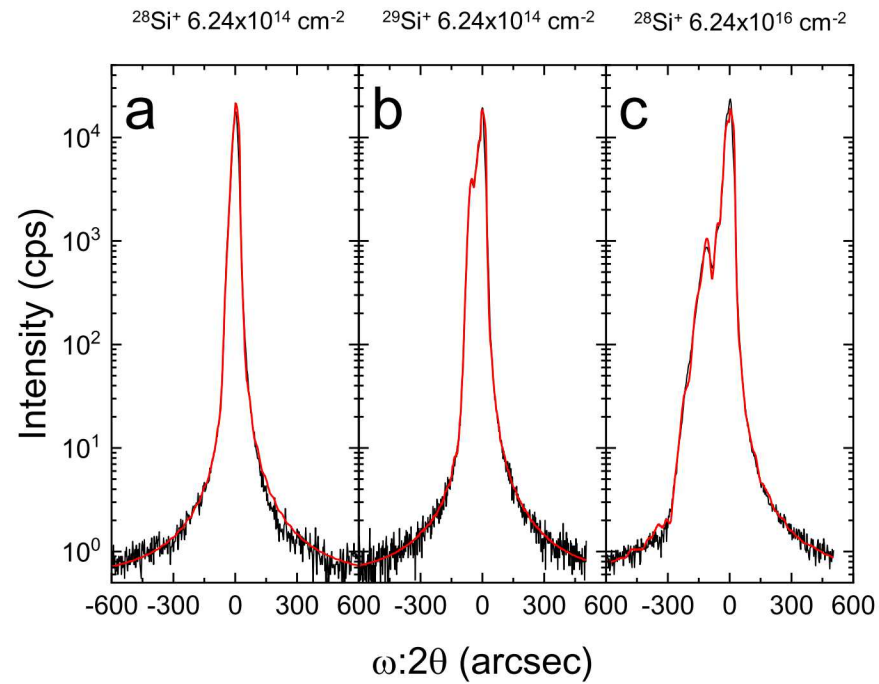
$$\tau_{Def}^{-1} = \frac{\omega(k)^4 \delta^3 \Gamma_i}{4\pi v_j^3(k)}$$

$$\Gamma_i = x_i \left[\left(\frac{\Delta M_i}{M} \right)^2 + 2 \left(\left(\frac{\Delta G_i}{G} \right) - 2 * 3.2\gamma \left(\frac{\Delta \delta_i}{\delta} \right) \right)^2 \right]$$

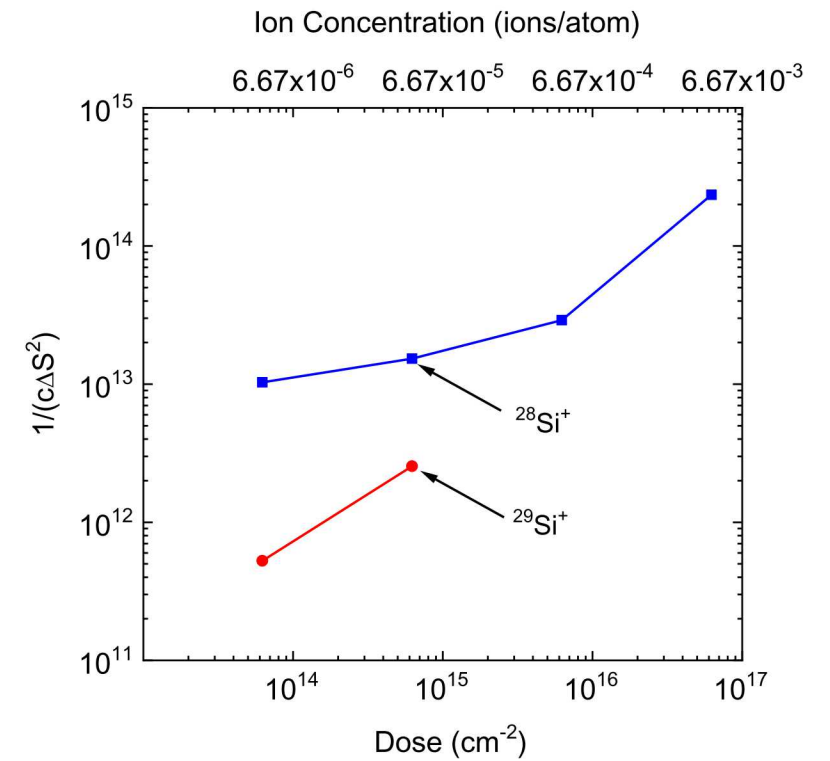
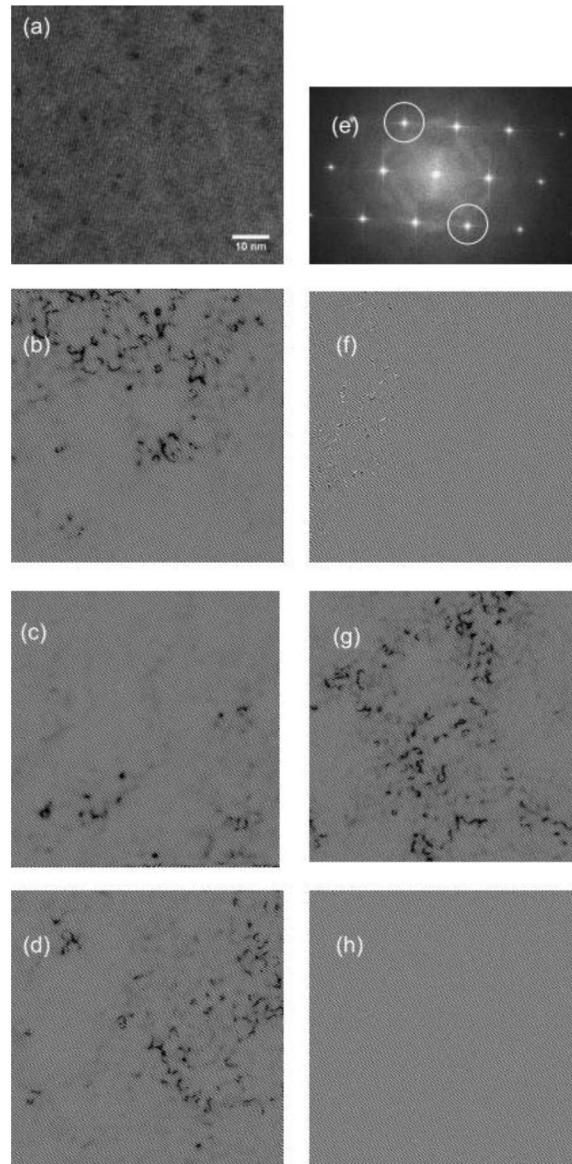
$$\Gamma_i = x_i \left[\left(\frac{\Delta M_i}{M} \right)^2 + c(\Delta S_{G_i, \delta_i})^2 \right]$$



$^{28,29}\text{Si}^+$ in silicon



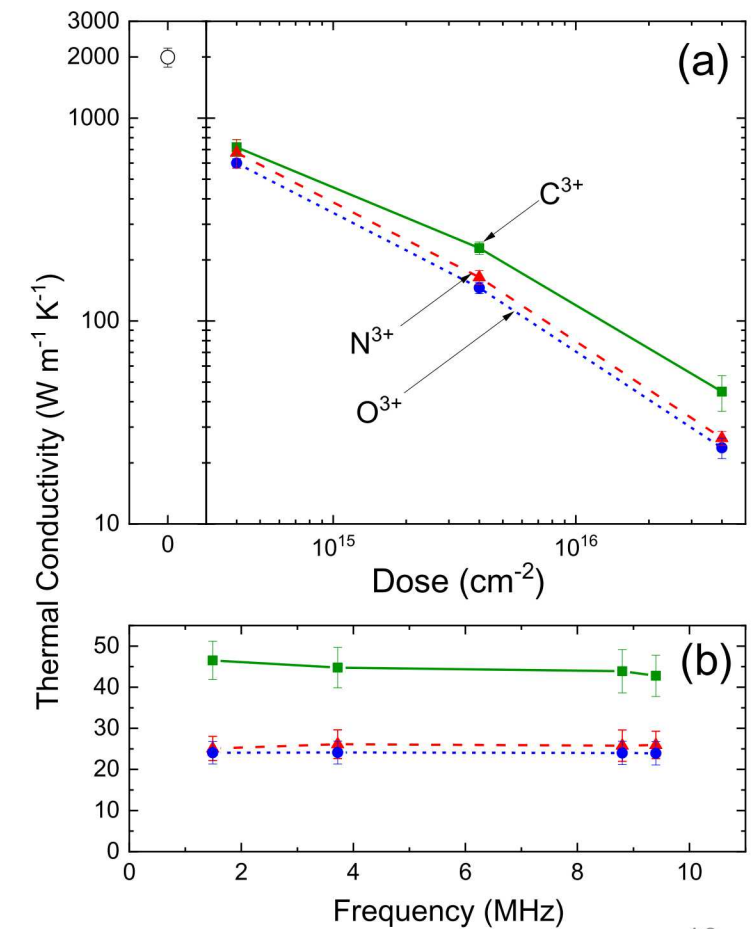
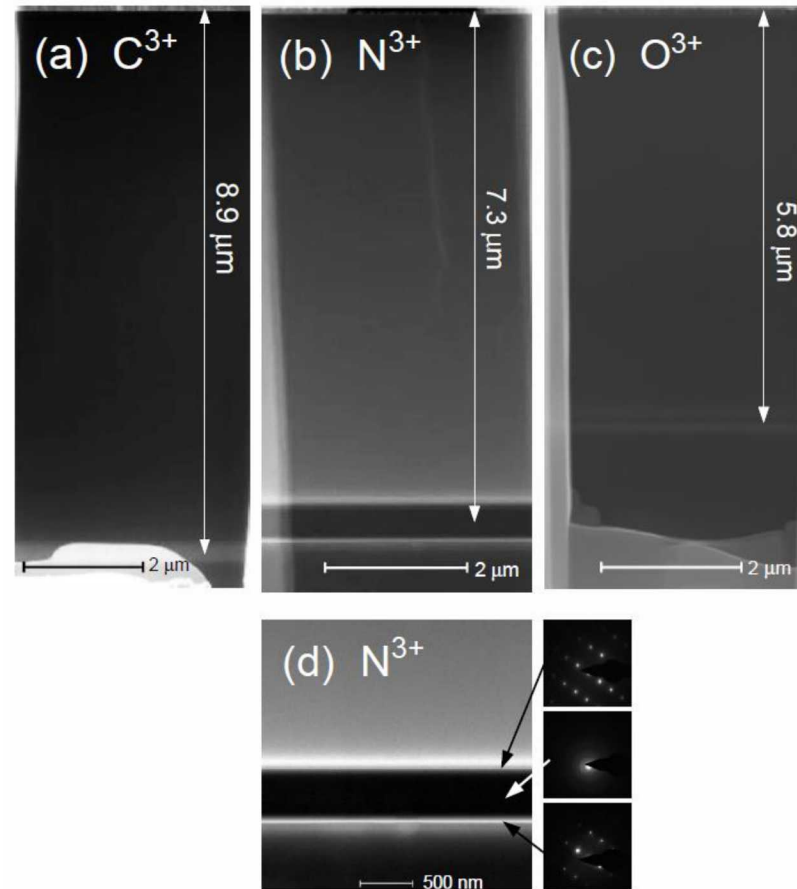
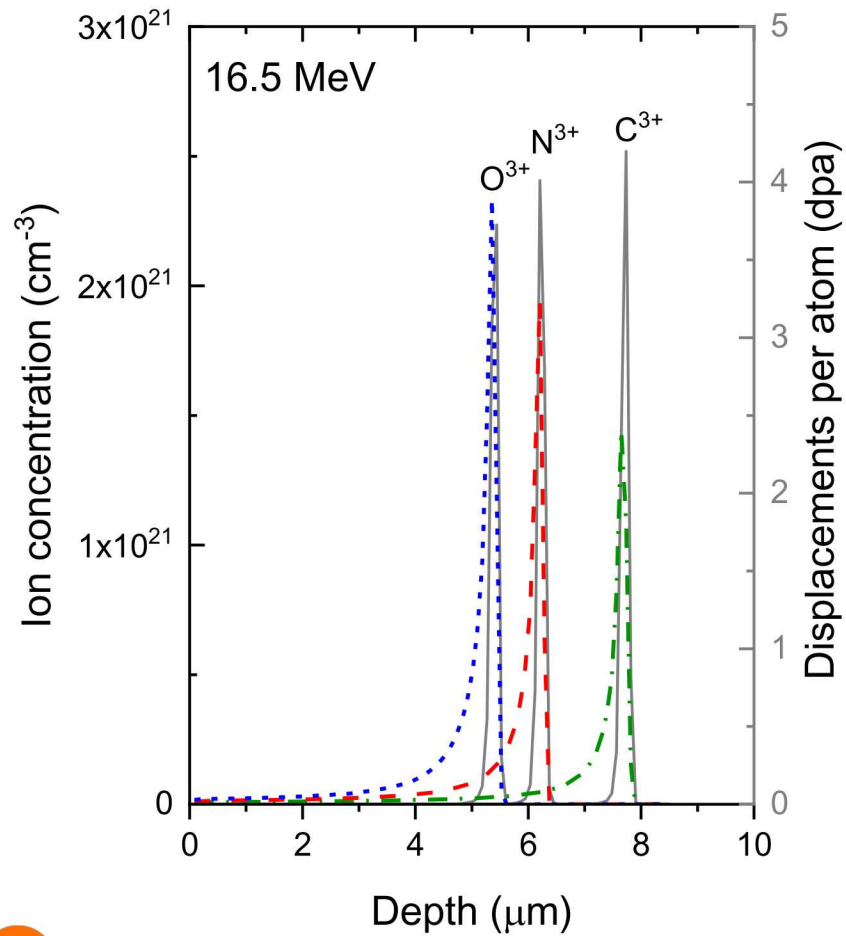
$$\Gamma_i = x_i \left[\left(\frac{\Delta M_i}{M} \right)^2 + c(\Delta S_{G_i, \delta_i})^2 \right]$$



C^{3+} , N^{3+} , O^{3+} in diamond

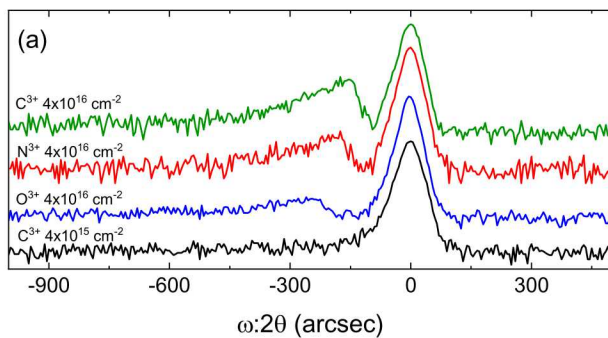


Image source: <https://e6cvd.com/us/>

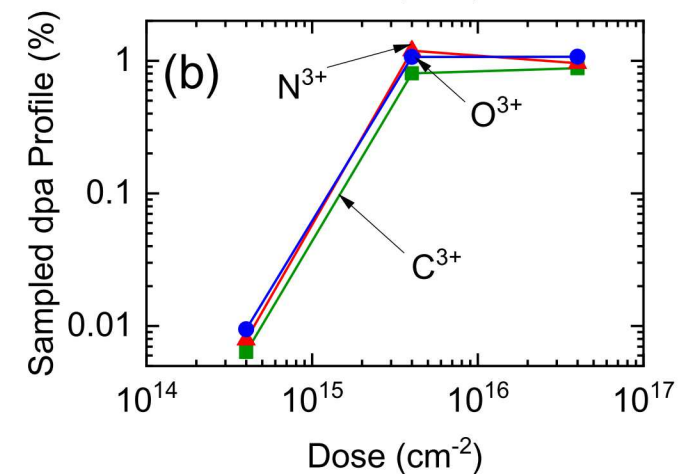
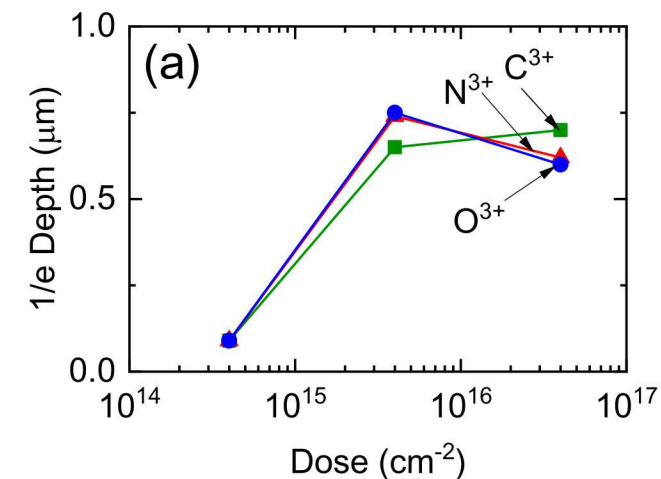
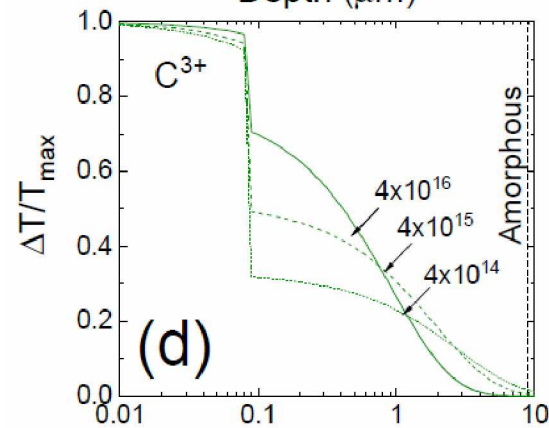
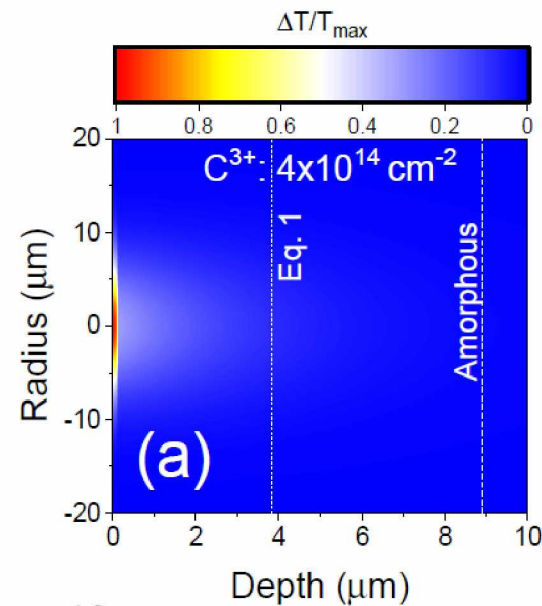
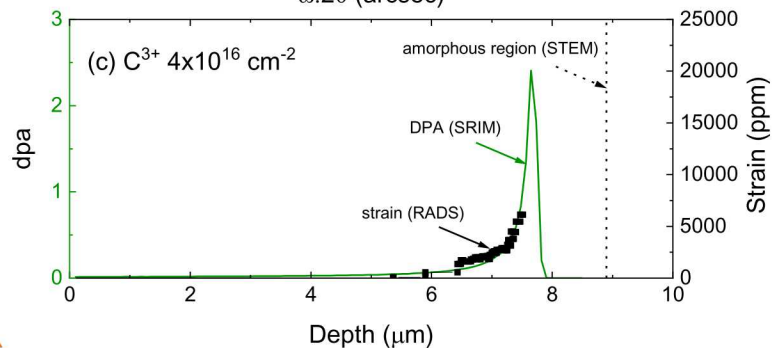
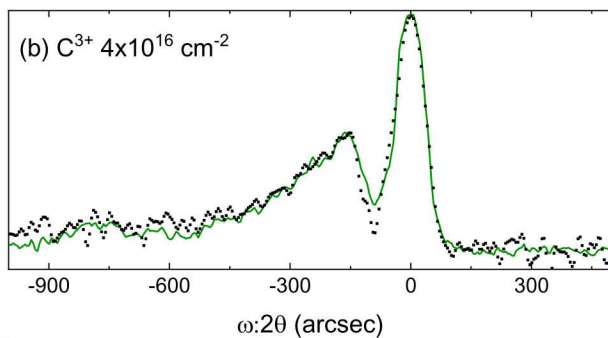


C³⁺, N³⁺, O³⁺ in diamond

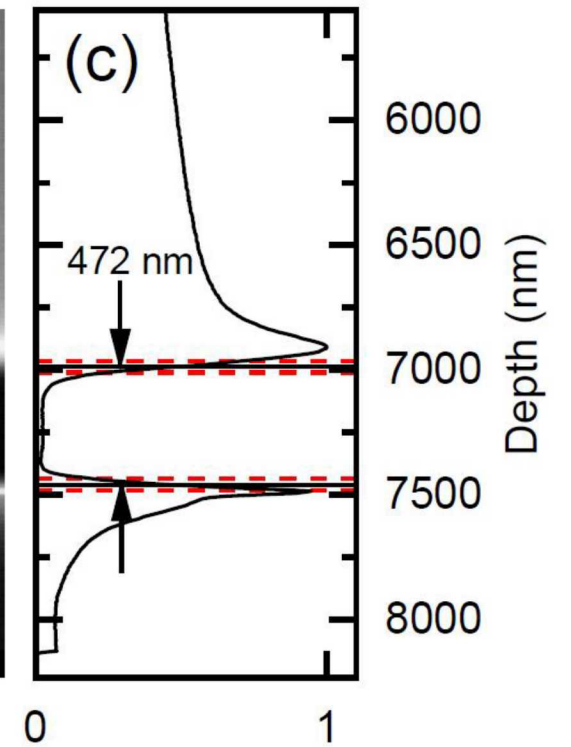
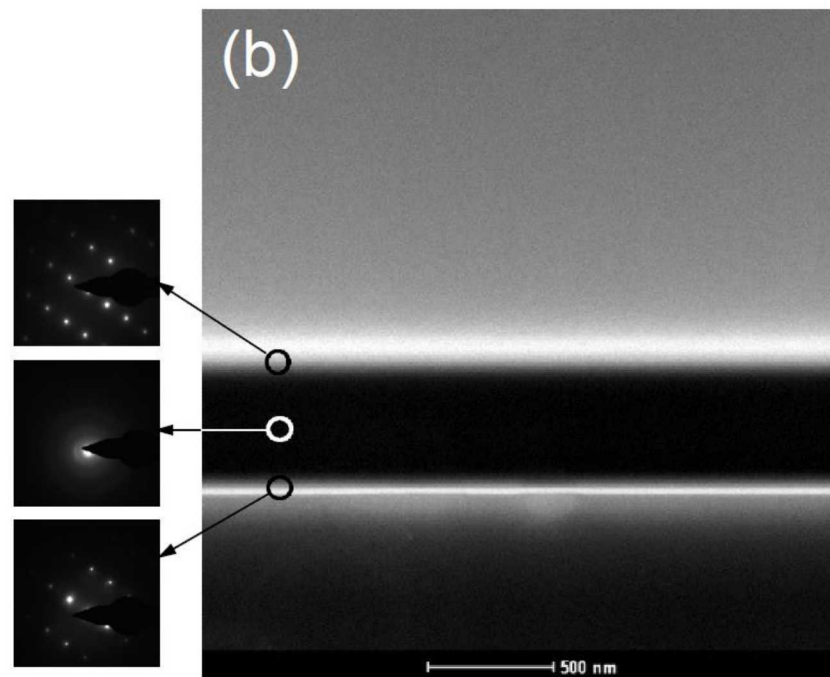
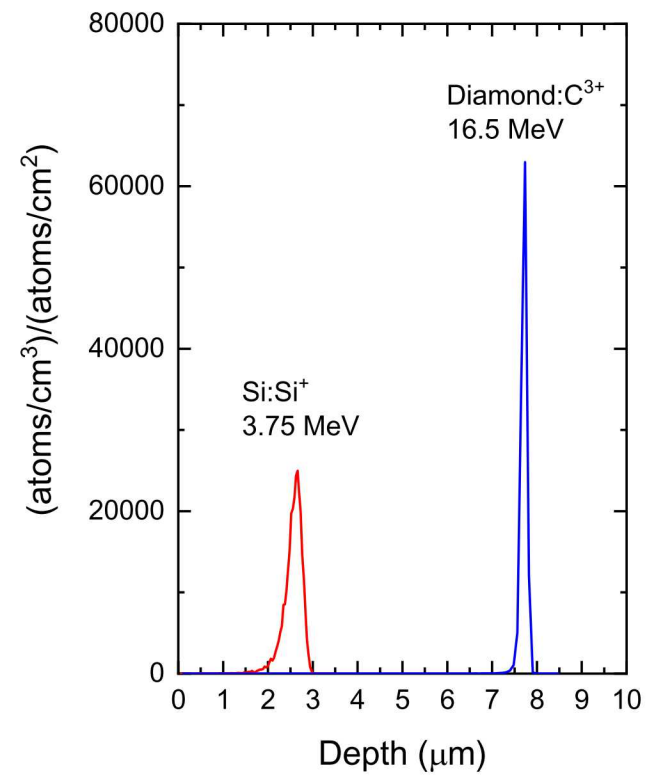
Offset Log Intensity (a.u.)



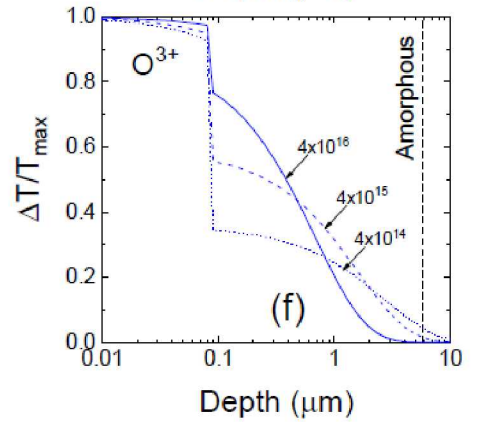
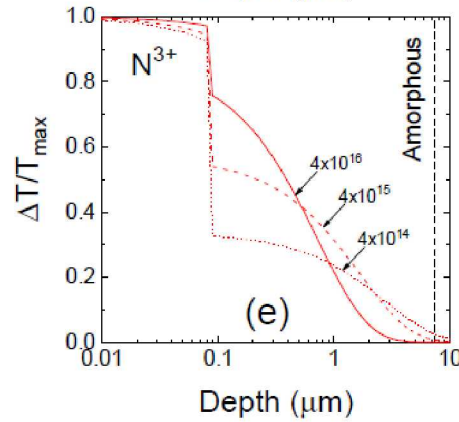
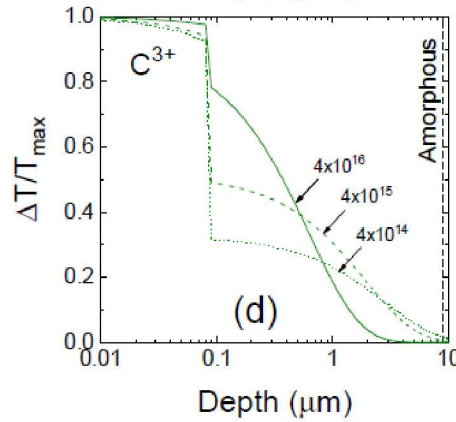
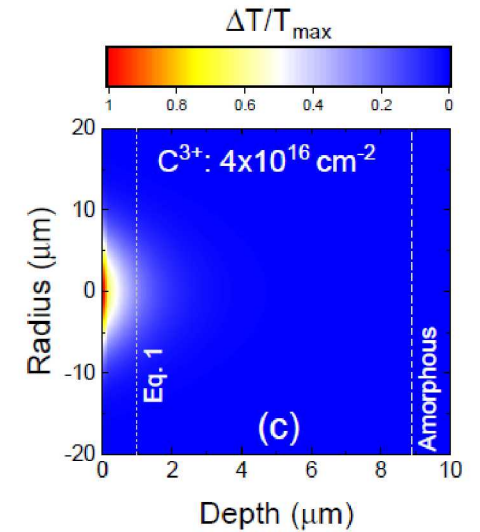
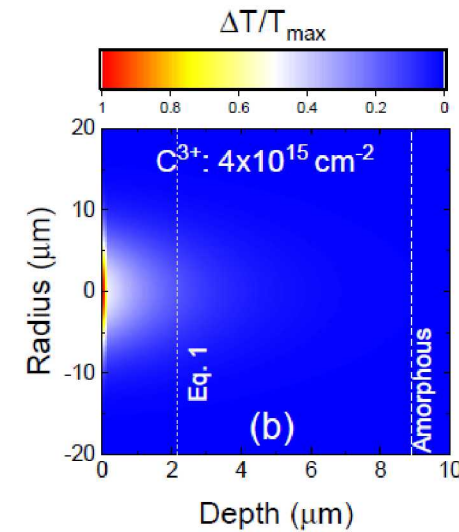
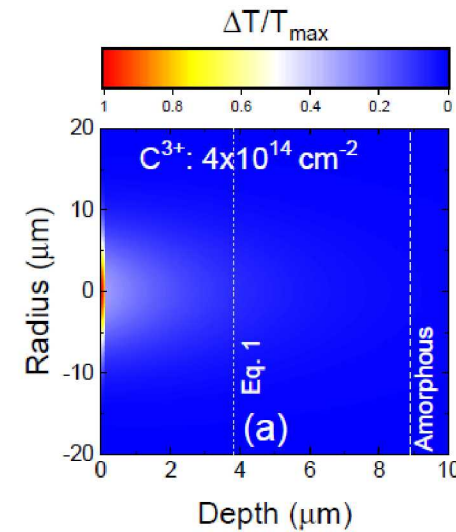
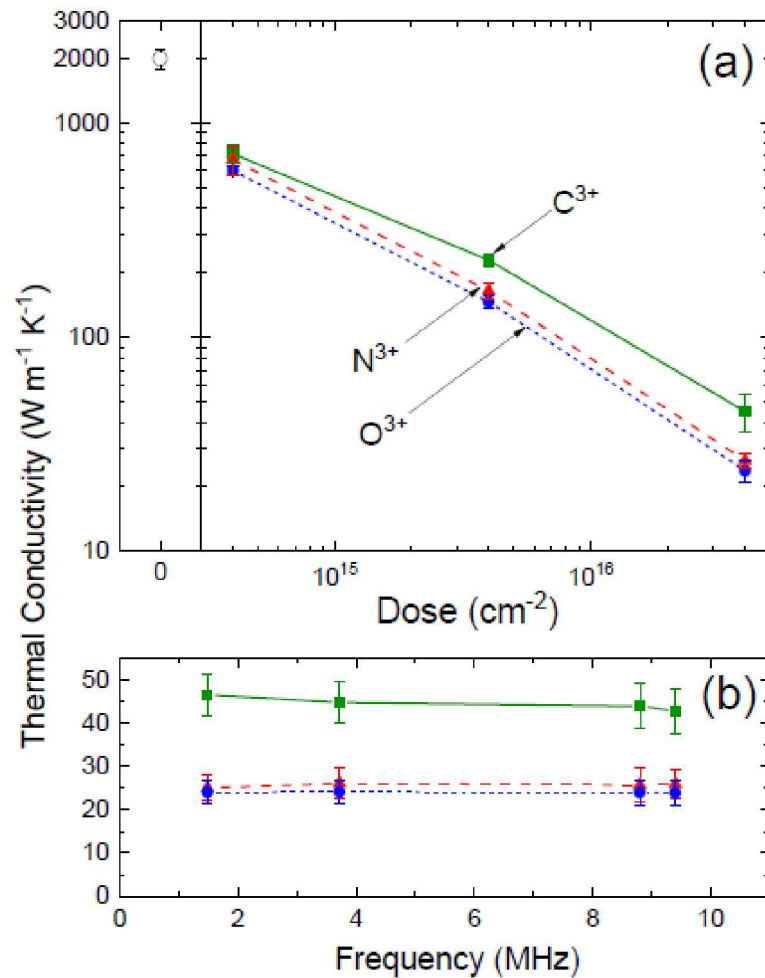
Log Intensity (a.u.)



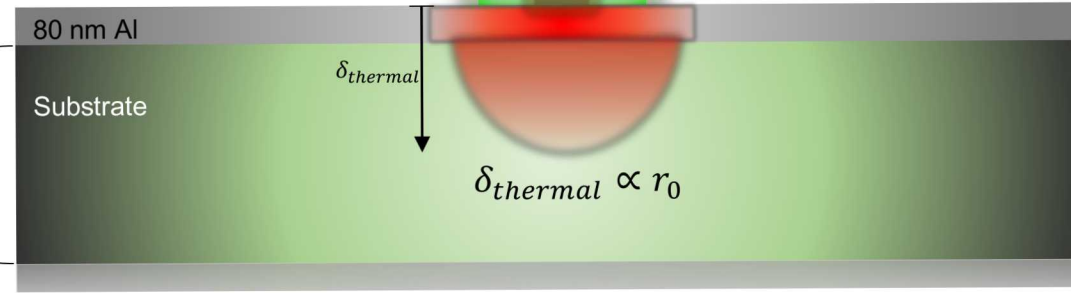
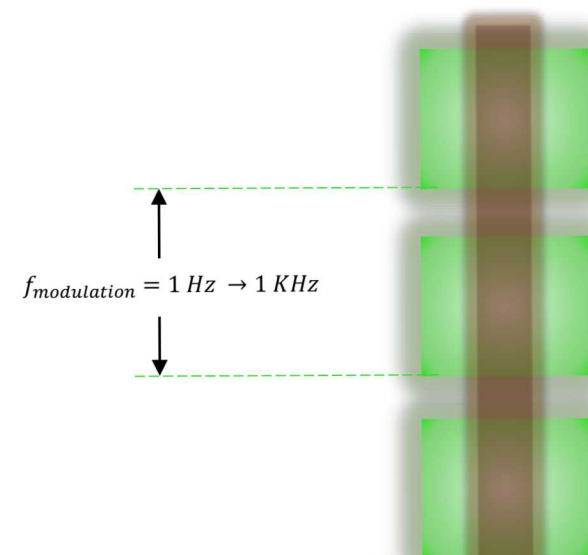
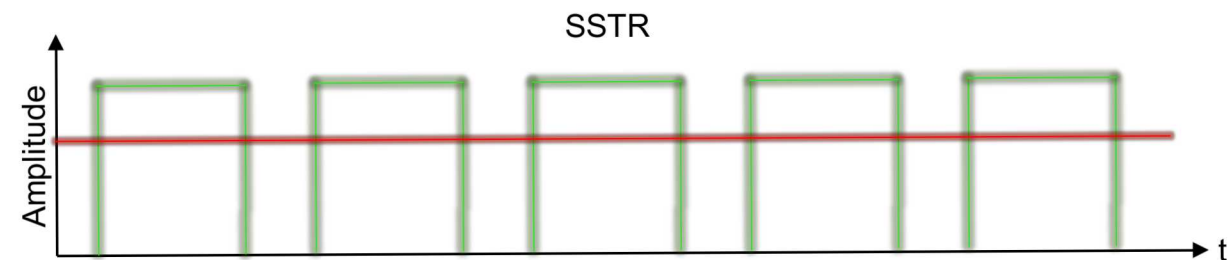
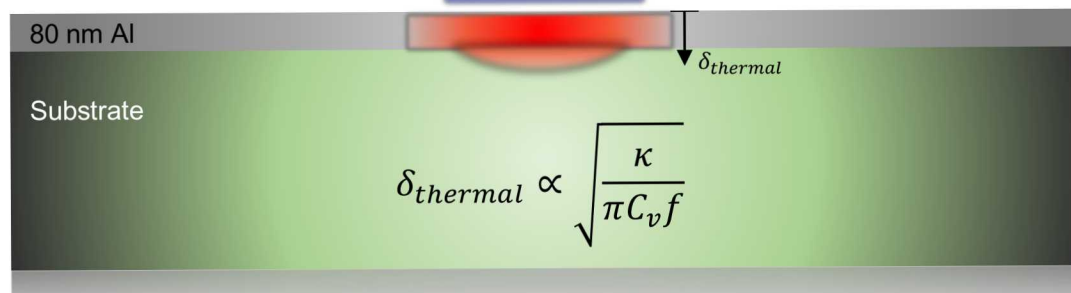
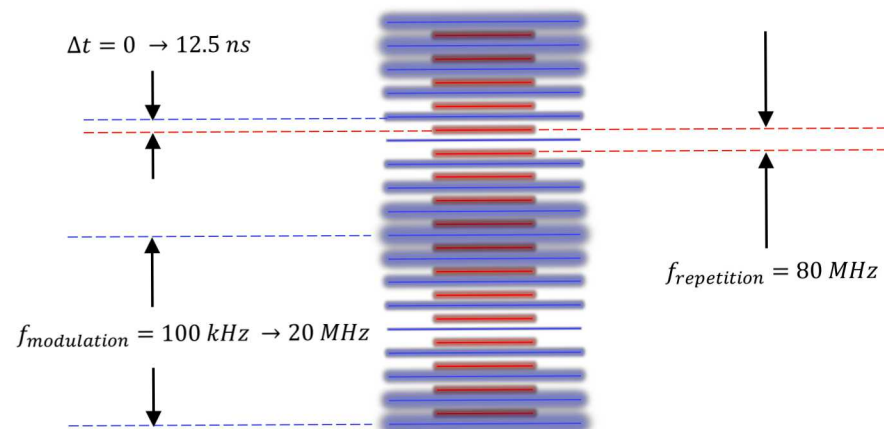
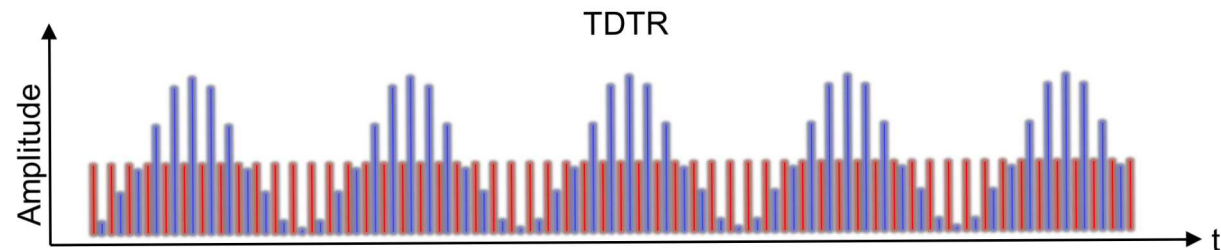
Buried thermal resistances



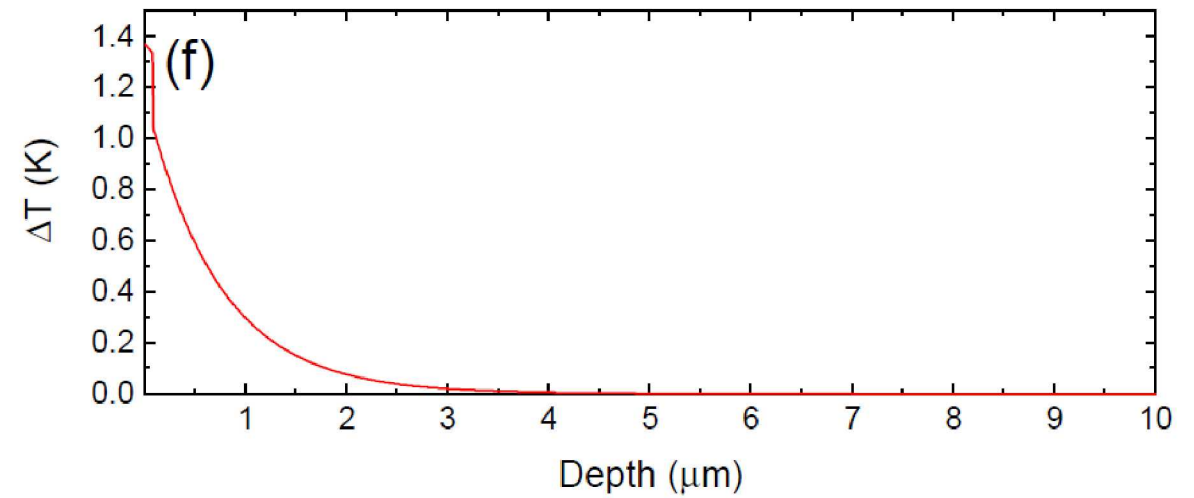
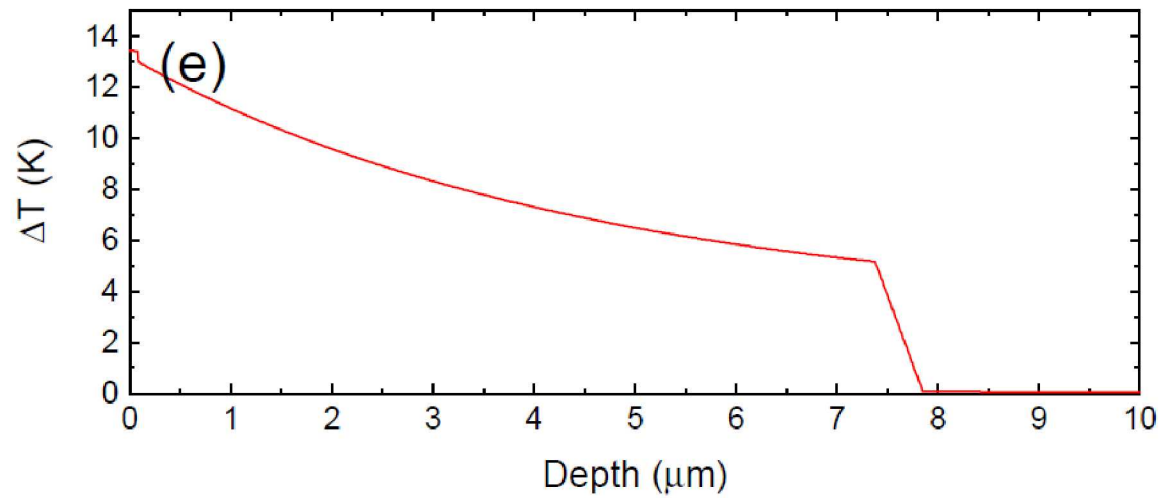
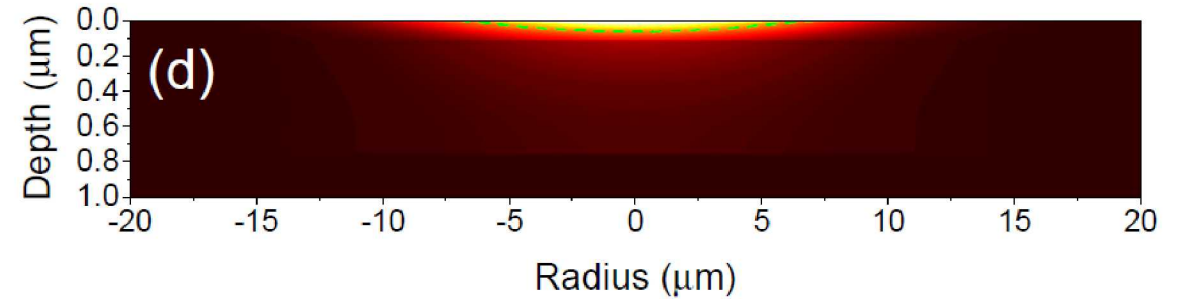
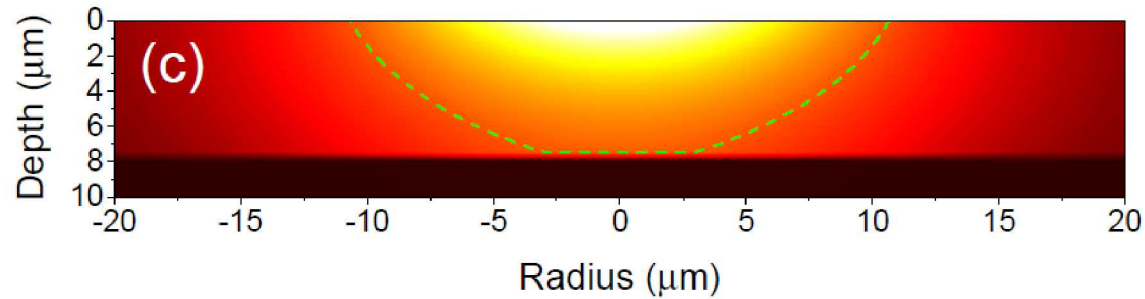
Thermal conductivity, polycrystalline region



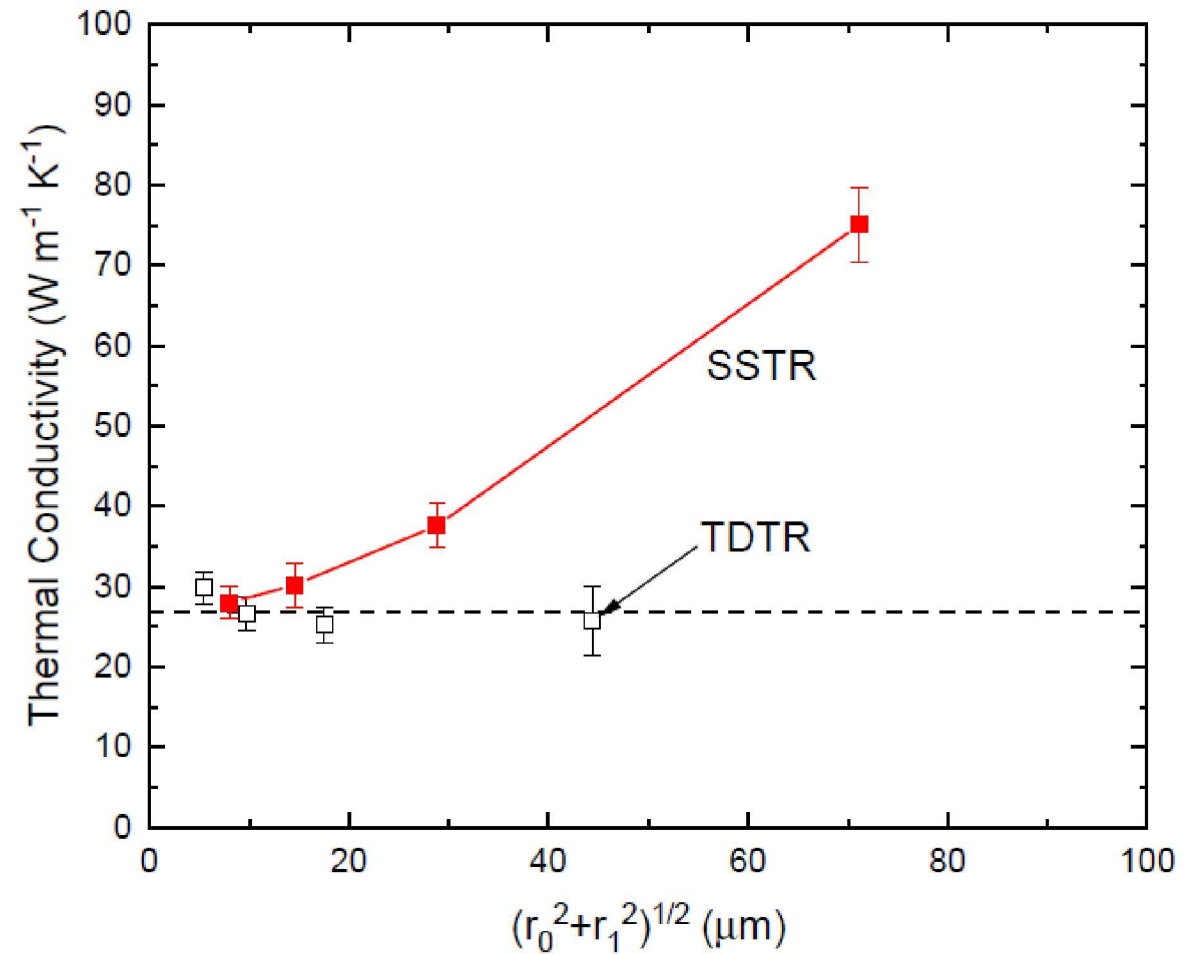
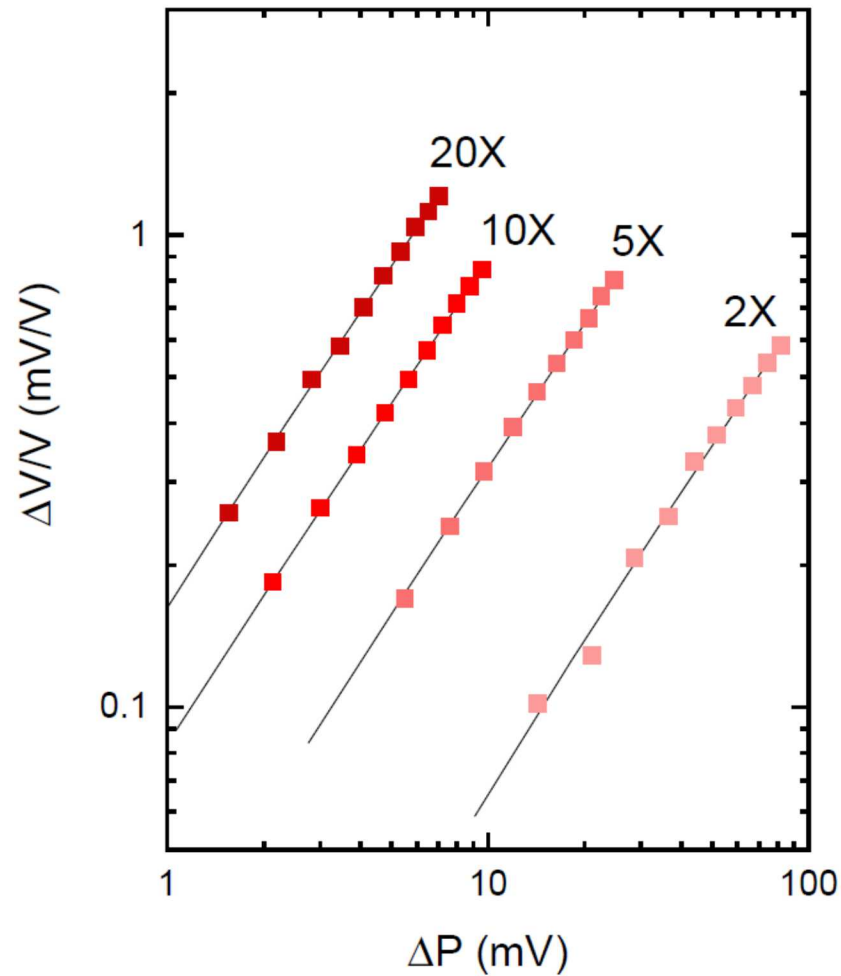
TDTR & SSTR



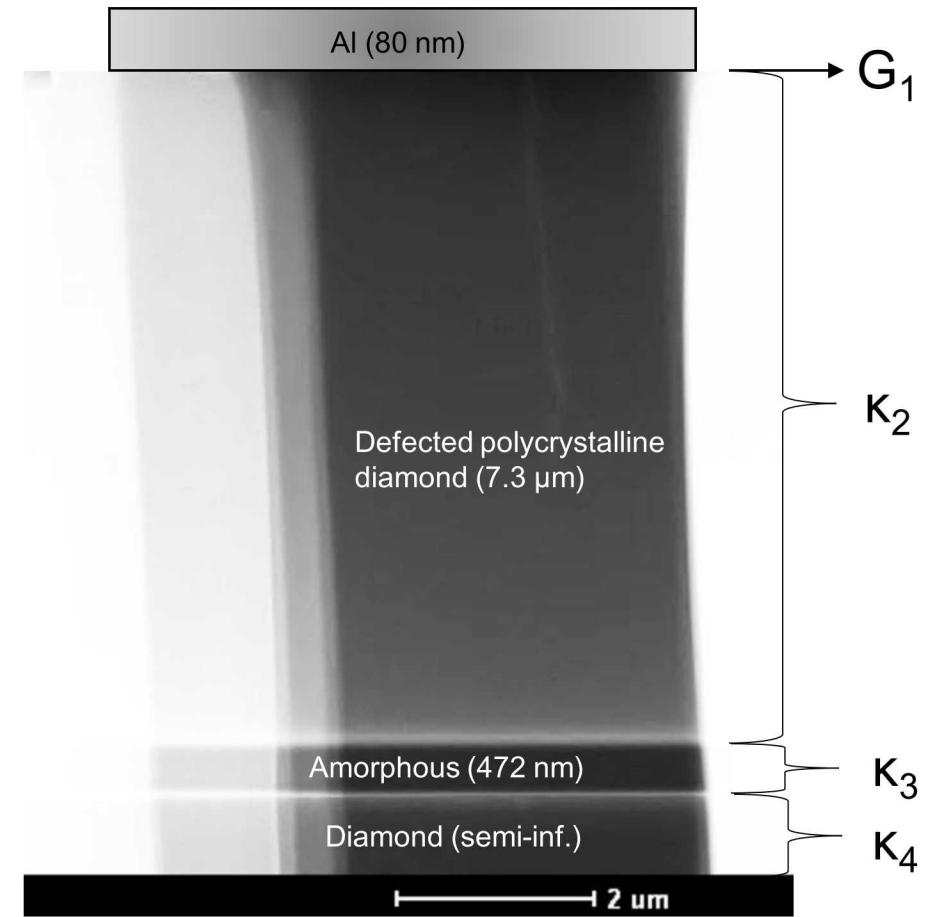
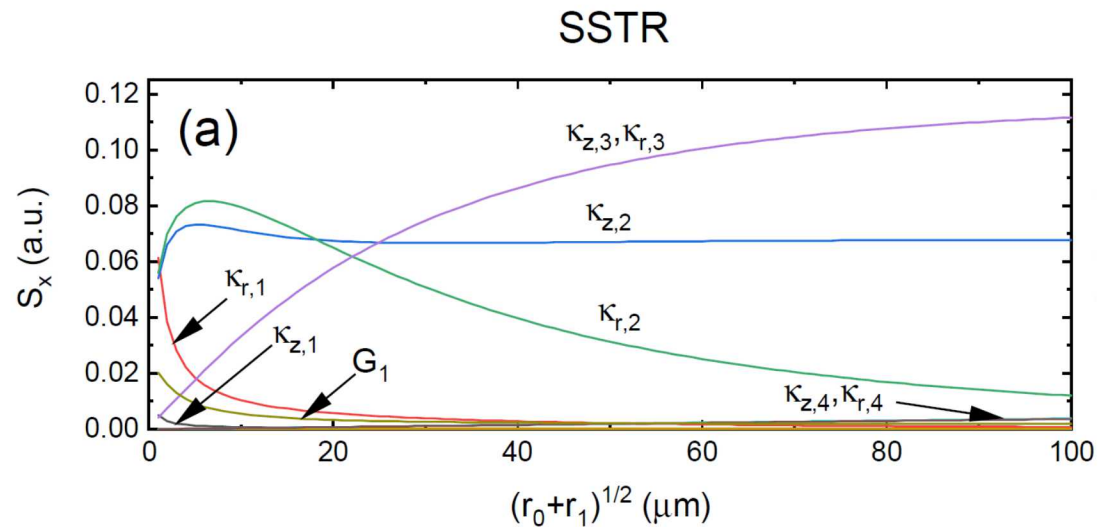
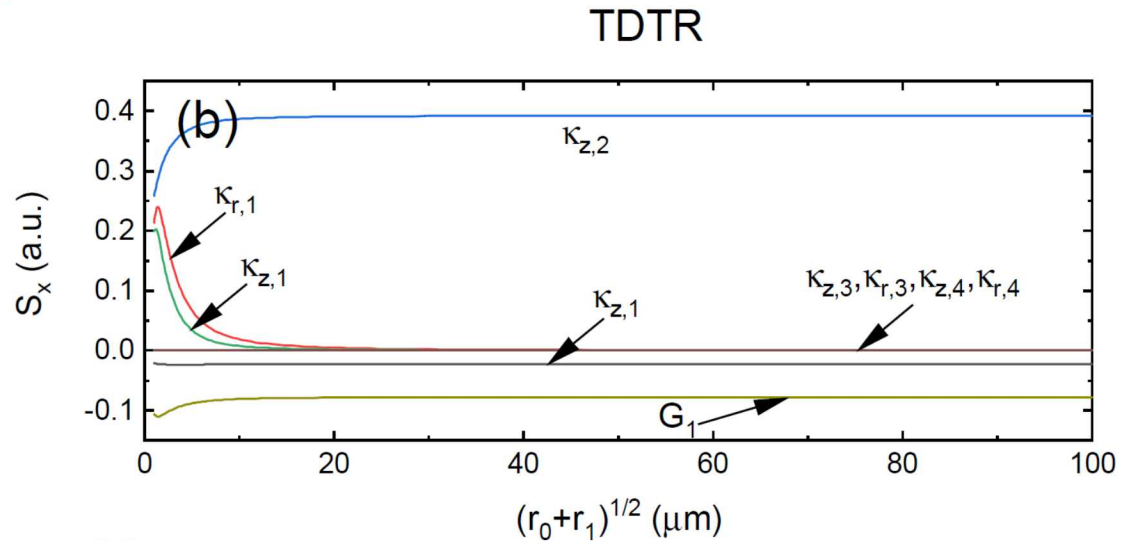
Increase TPD with SSTR



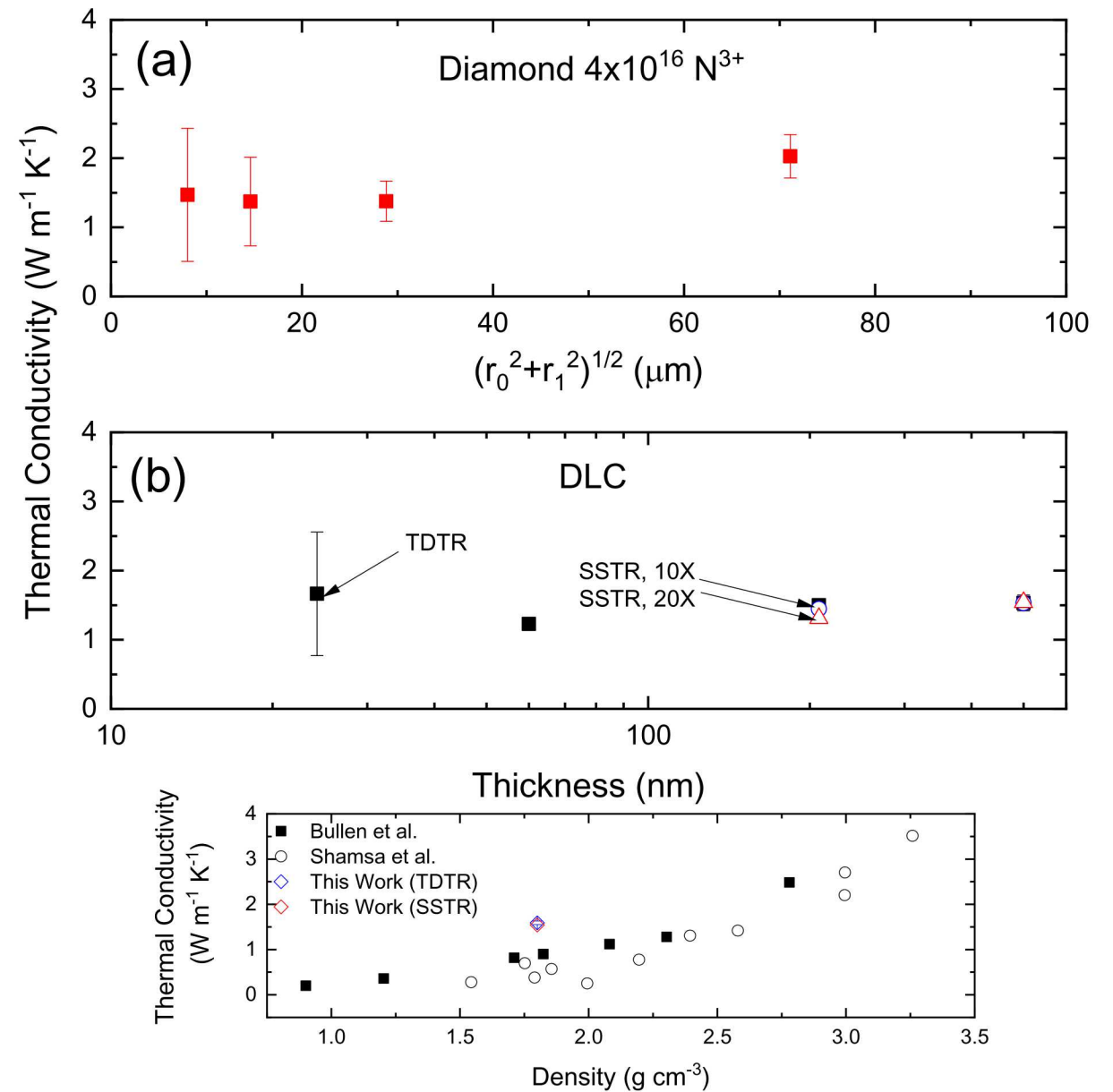
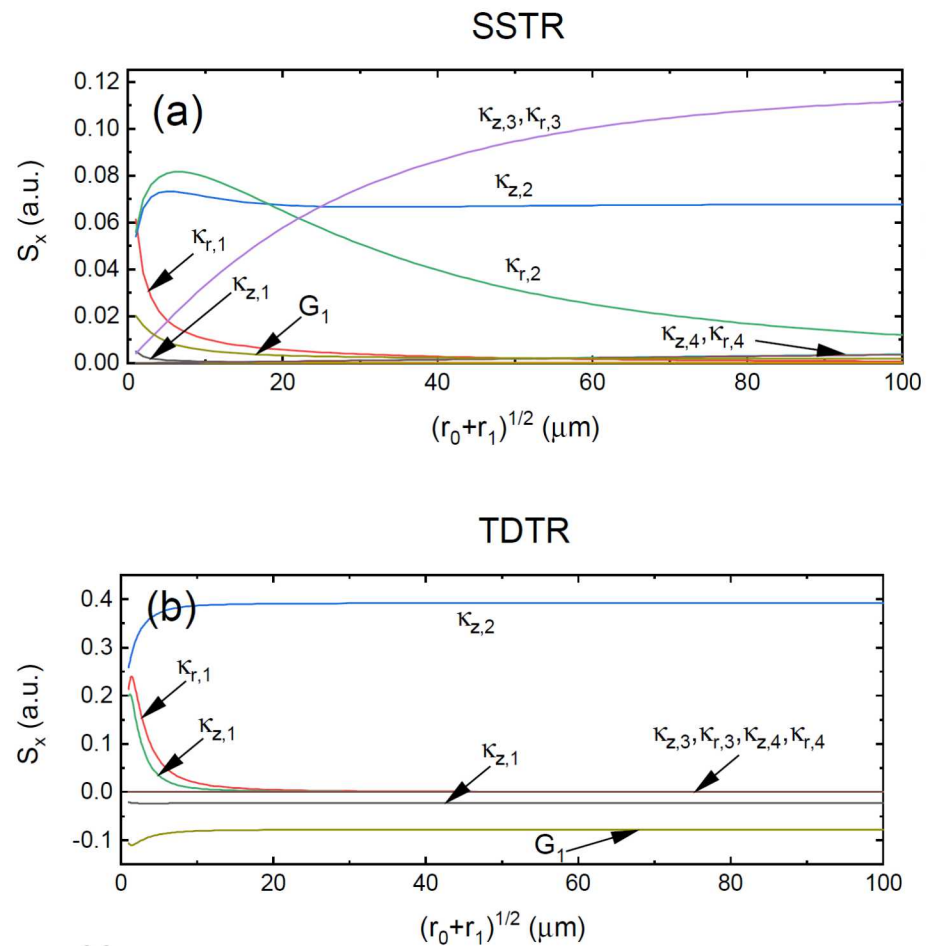
SSTR Measurements, two-layer model



Sensitivity of SSTR

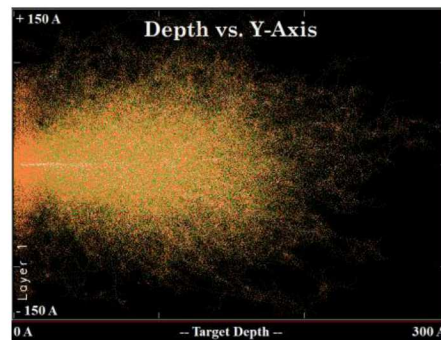


SSTR, four-layer model



Summary

- Ion beams used as tools to probe scattering mechanisms of long established scattering models
 - Si: Si^{28+} , Si^{29+} 3.75 MeV
 - Diamond: C^{3+} , N^{3+} , O^{3+} 16.5 MeV
- Diffuse regions of point and extended defects in silicon, localized amorphous region at end of range in diamond
- Orders of magnitude reductions in thermal conductivity achievable while still retaining structure within the lattice
- Unique means of producing defects in a controlled manner



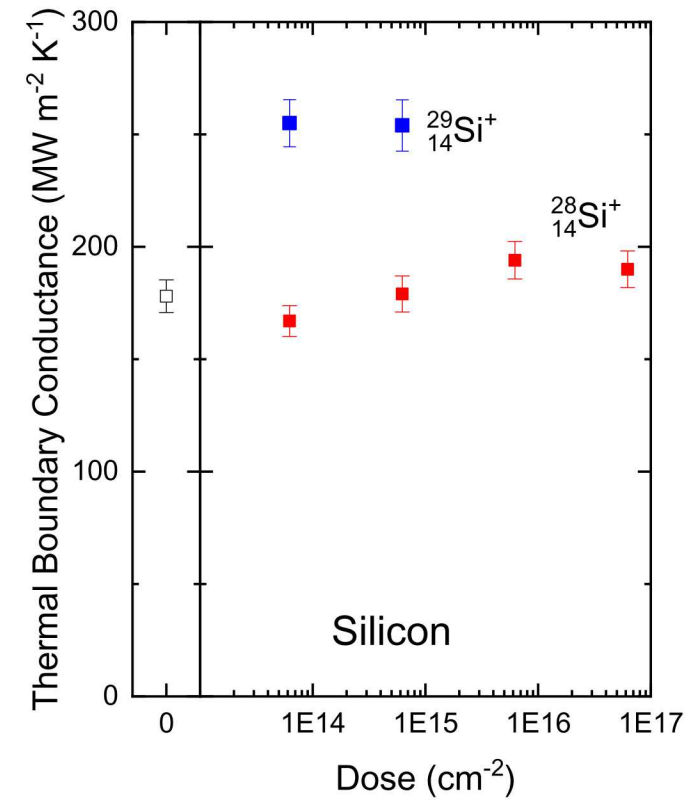
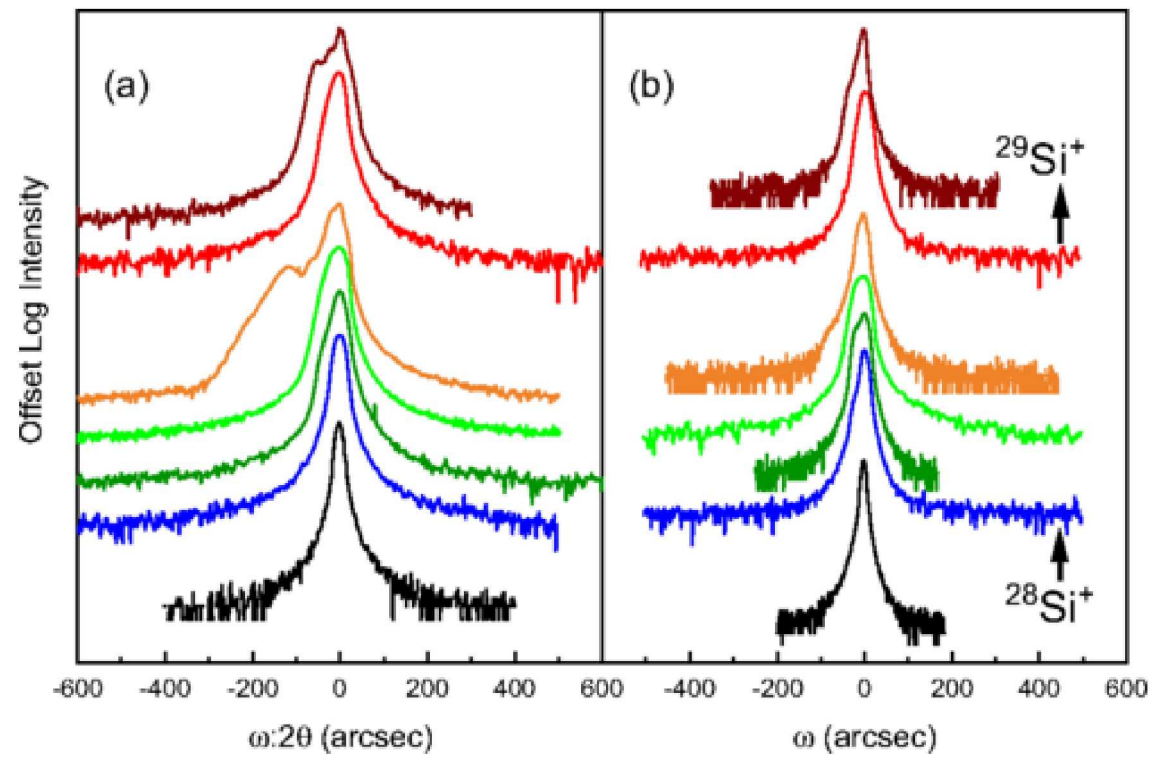
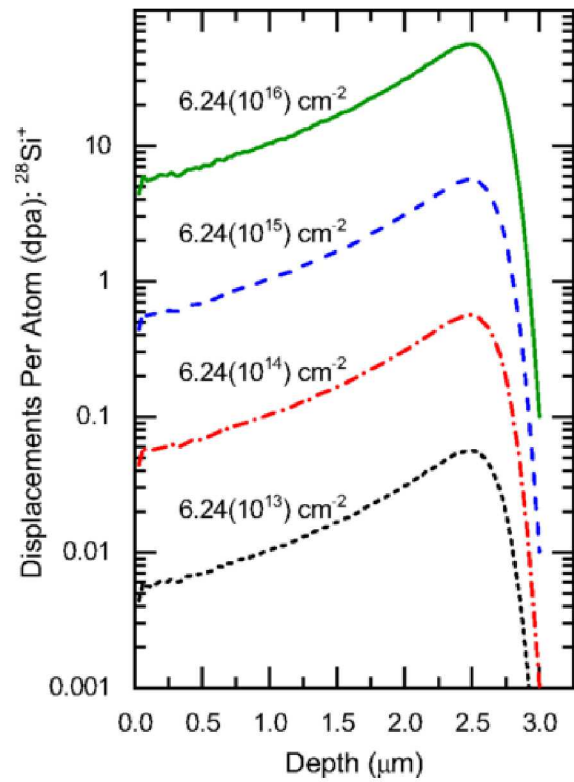
Thank you



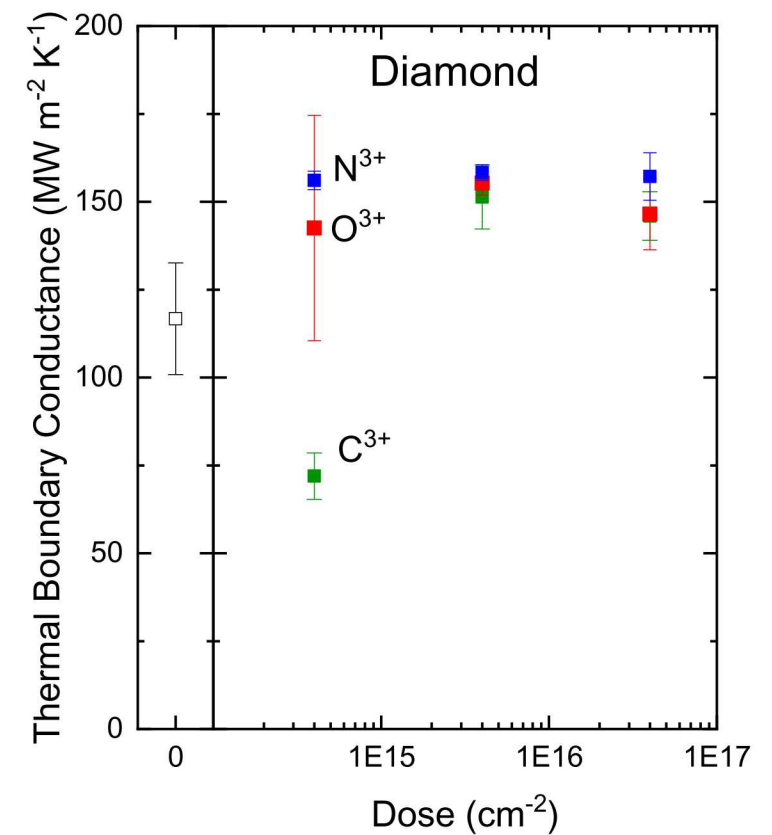
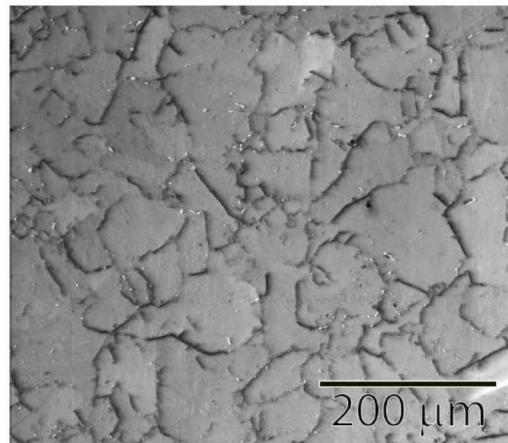
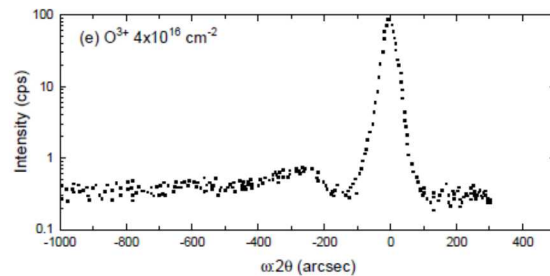
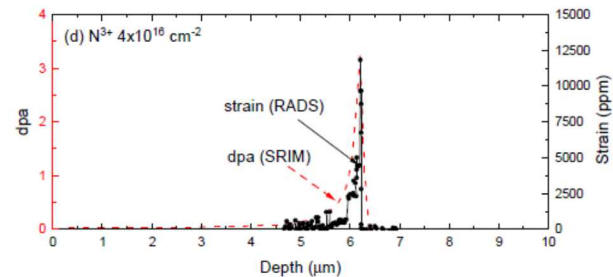
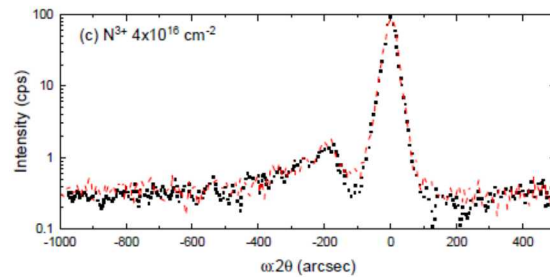
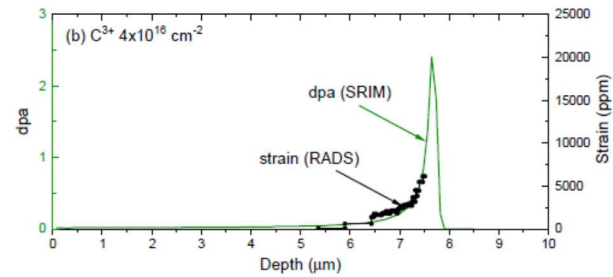
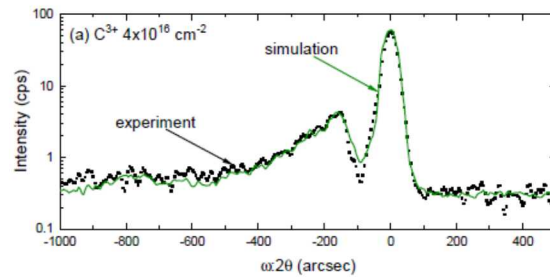
Supplementary Material



$^{28,29}\text{Si}^+$ in silicon



C³⁺, N³⁺, O³⁺ in diamond



Diamond/SSTR

